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PATENT 03371-P0005A LHR

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants	Lynn David Bollinger, et al.
Serial No. 09/693,117	Filing Date: October 20, 2000
Title of Application	Method for Rapid Thermal Processing of Substrates
Group Art Unit 2812	2812

#9 4-13-02 RANGE

Assistant Commissioner for Patents Washington, DC 20231

Preliminary Amendment

Dear Sir:

Amendment Revisions

RECEIVED APR-2 2002 IC 2800 MAIL ROOM

In the Specification

Please substitute the first paragraph on page 33 through the third paragraph on page 34 with the following paragraphs.

Clean Version of Each Replacement Paragraph of the Specification



For this approximate physical model, we consider the substrate as three equal layers each of thickness $\Delta h/3$. We estimate the temperature rise of the top, directly heated layer and then compare this to an estimate of the heat transferred through the

<u>Mailing Certificate</u>: I hereby certify that this correspondence is today being deposited with the U.S. Postal Service as *First Class Mail* in an envelope addressed to: Commissioner for Patents and Trademarks; Washington, DC 20231.

March 19, 2002

Caroline Gahagan